

List of reference numbers:

- | | | |
|----|------|----------------------------------|
| | 5: | circuit board |
| | 10: | individual layer |
| 5 | 12: | conductor trench |
| | 14: | mount |
| | 16: | positioning formation |
| | 18: | metallization |
| | 20: | cooling groove |
| 10 | 22: | contact opening |
| | 24: | electrically conductive adhesive |
| | 26: | mount |
| | 28: | component |
| | 30: | bonding wire |
| 15 | 32: | recess |
| | 34: | cooling channel |
| | 36: | cooling agent |
| | 38: | positioning pin |
| | 40: | waveguide |
| 20 | 42: | waveguide trench |
| | 44: | mirror |
| | 110: | blank for individual layer |
| | 112: | conductor trench preform |
| | 114: | mount preform |
| 25 | 116: | positioning formation preform |
| | 118: | pre-metallization |
| | 120: | cooling groove preform |
| | 122: | contact opening preform |

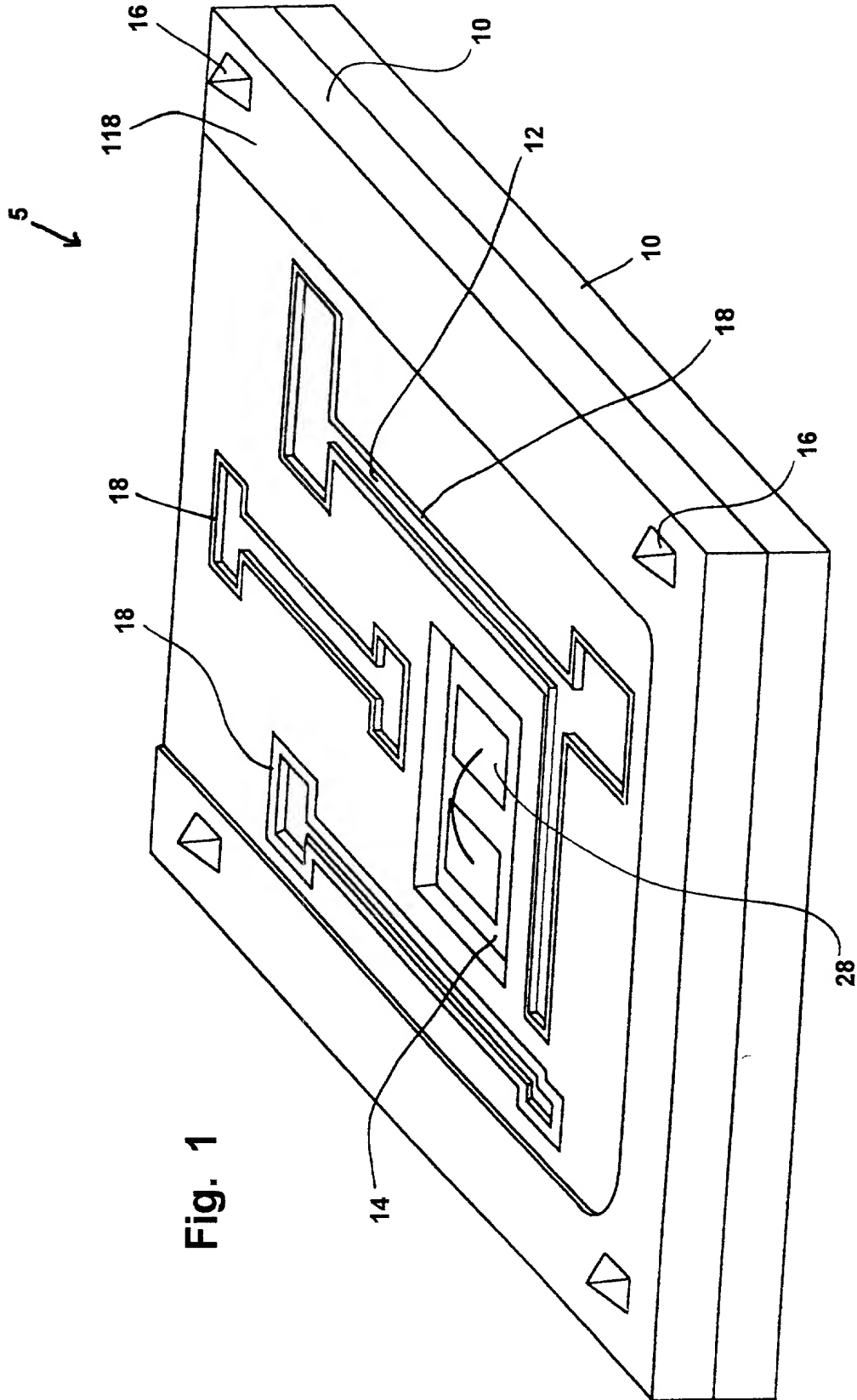


Fig. 1

Fig. 2

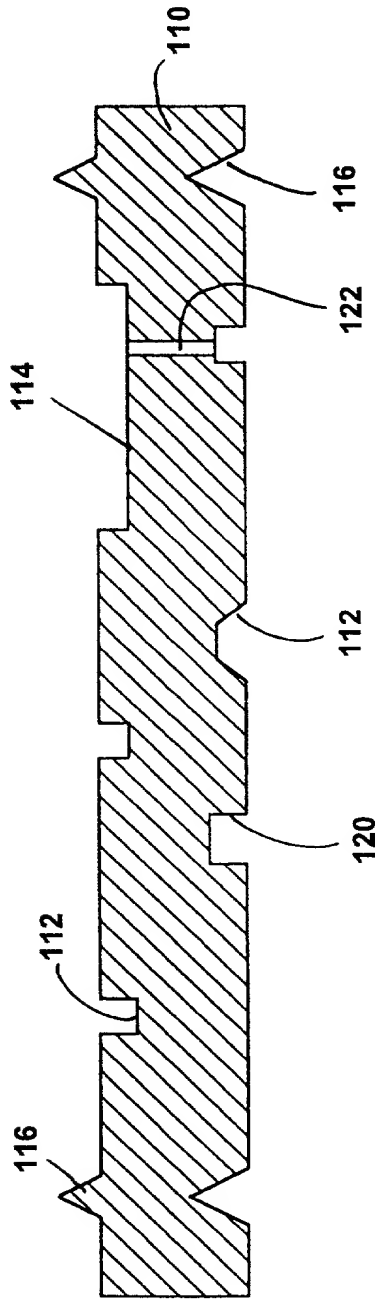


Fig. 3

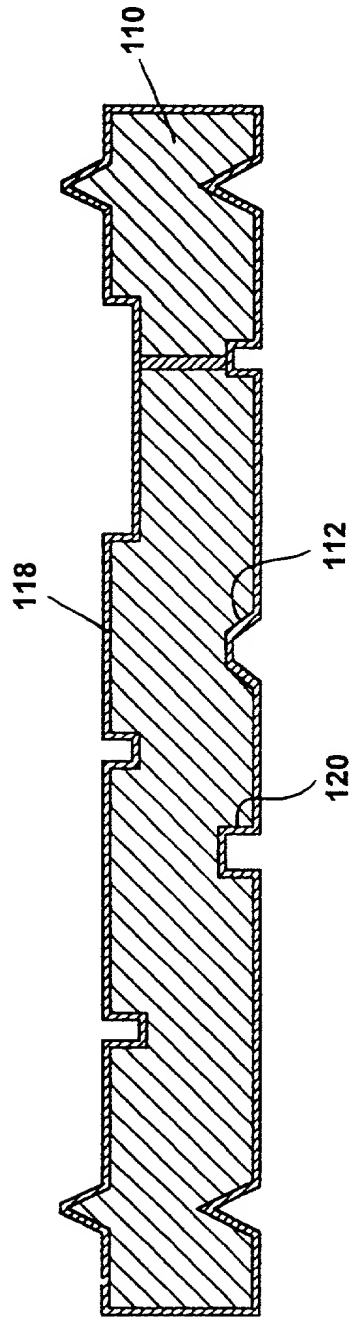
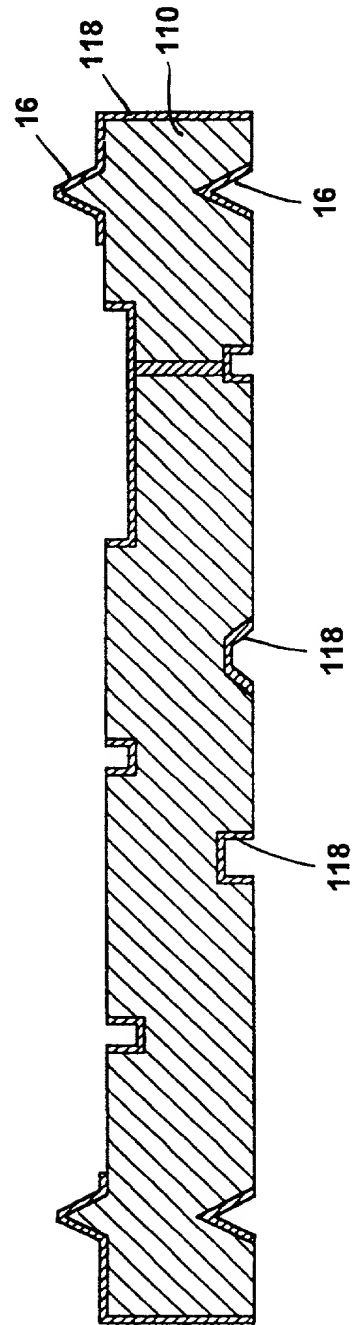
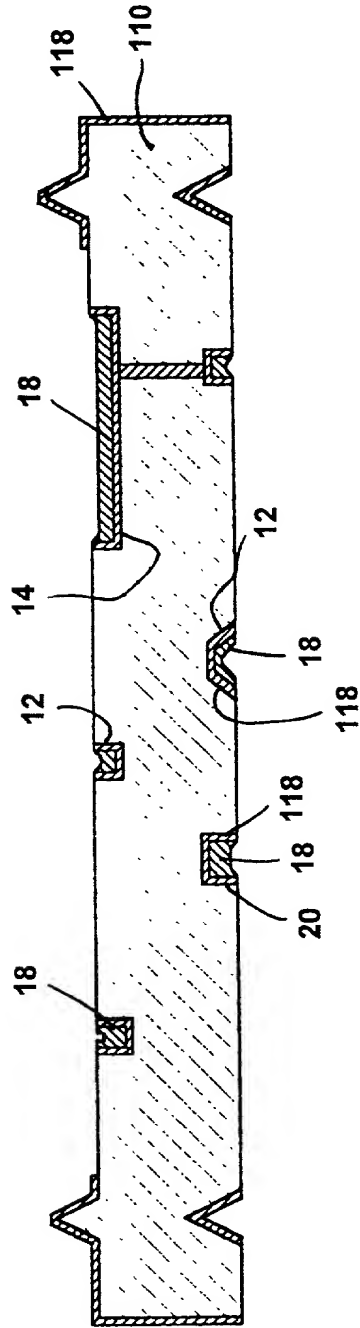


Fig. 4



5
9
10
11



5

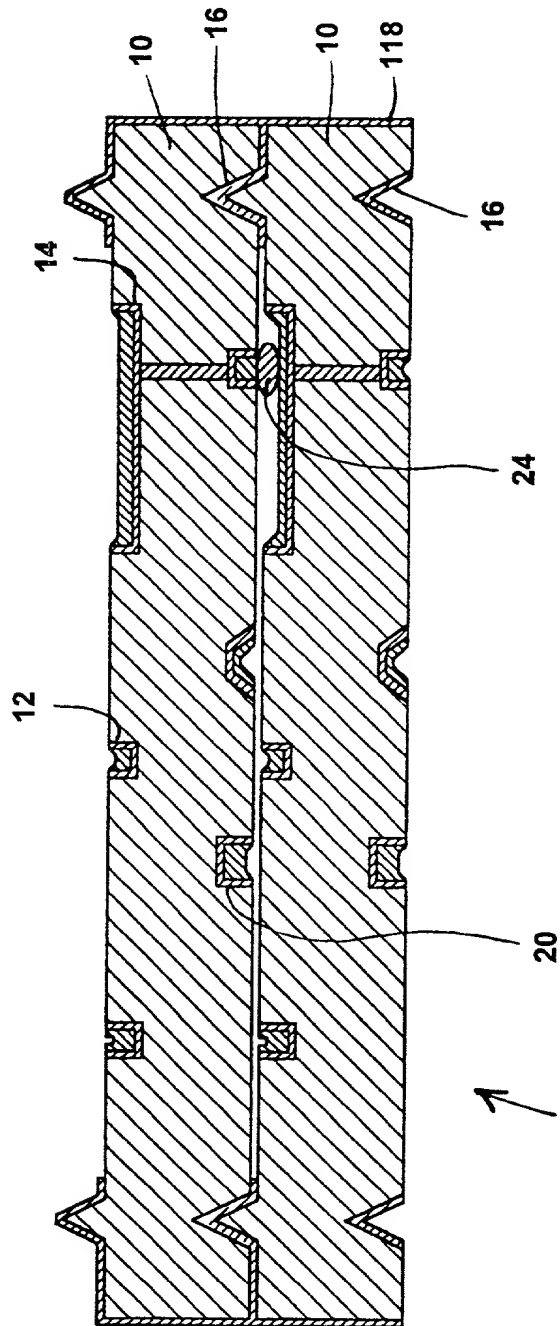


Fig. 7

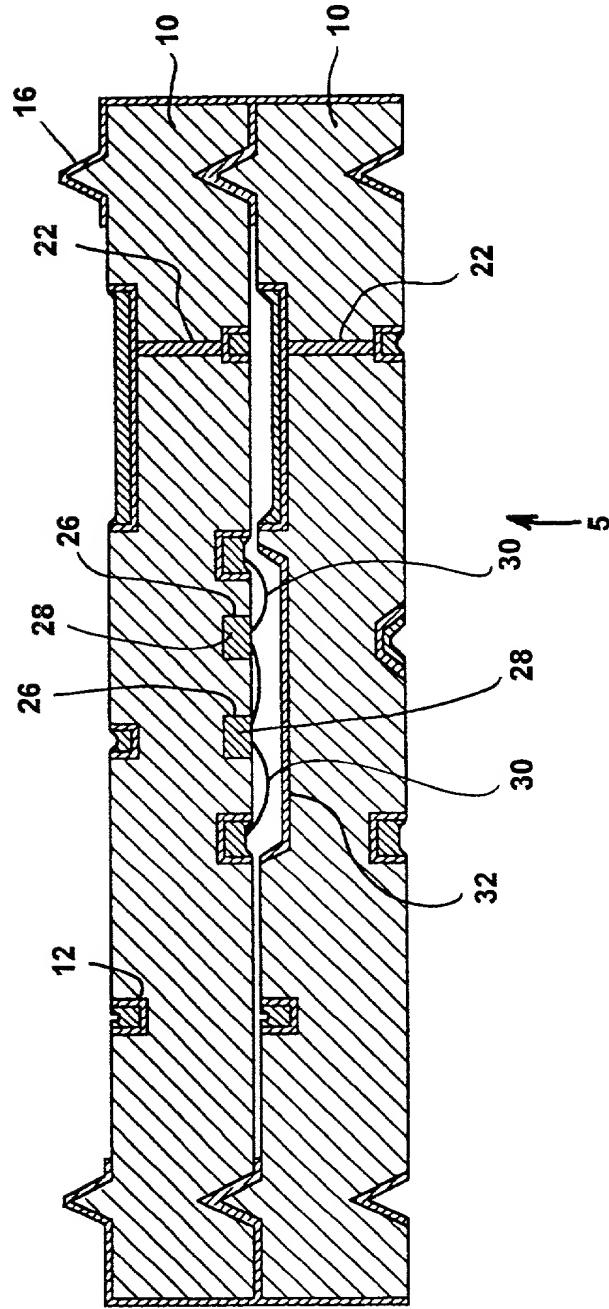


Fig. 8

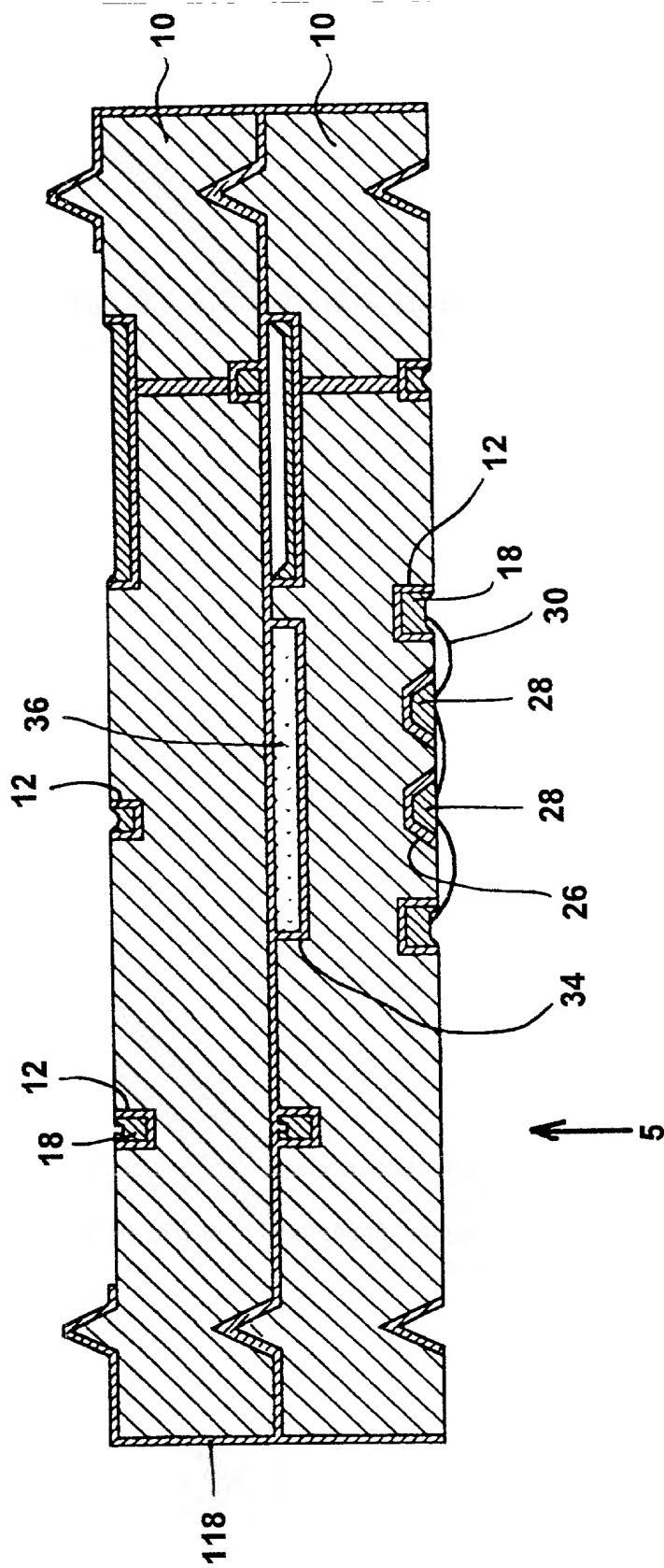
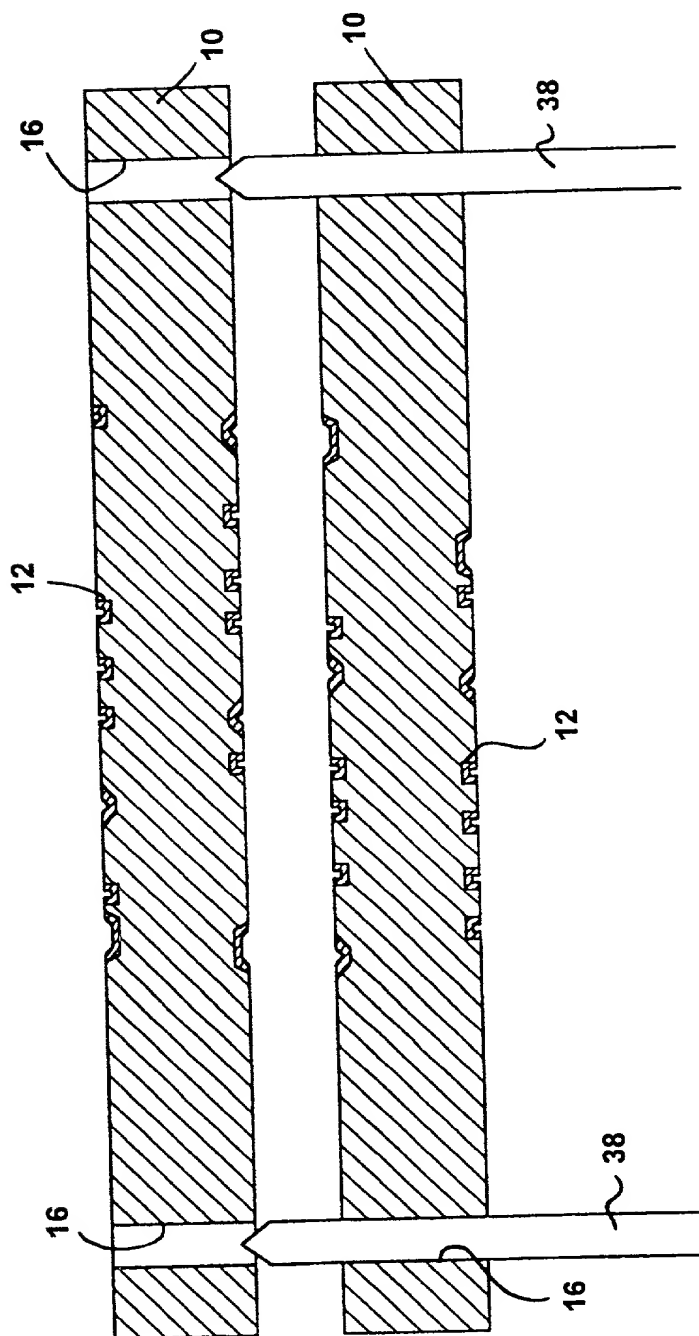


Fig. 9



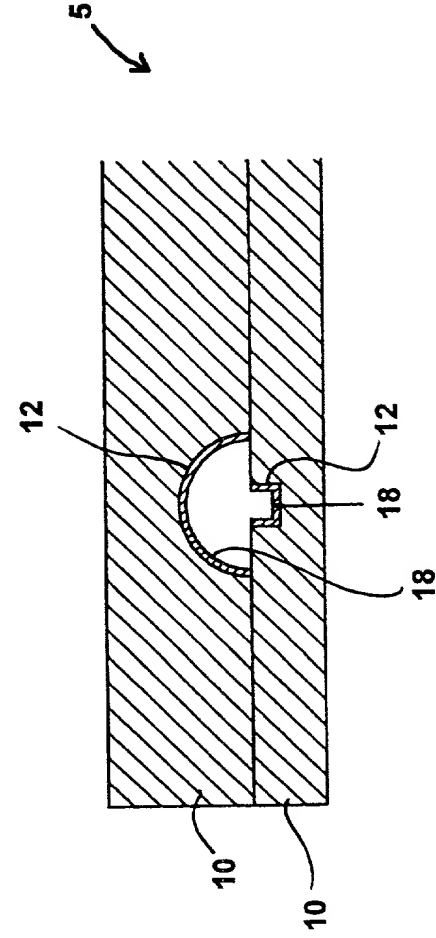


Fig. 10

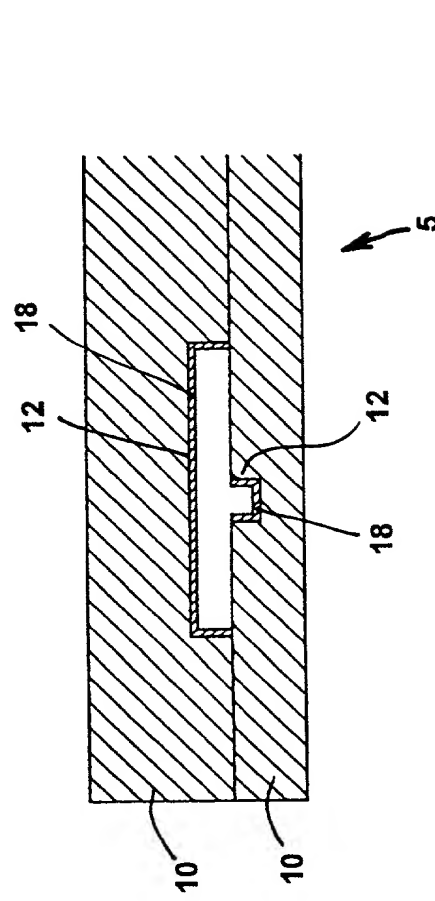


Fig. 11

Fig. 12

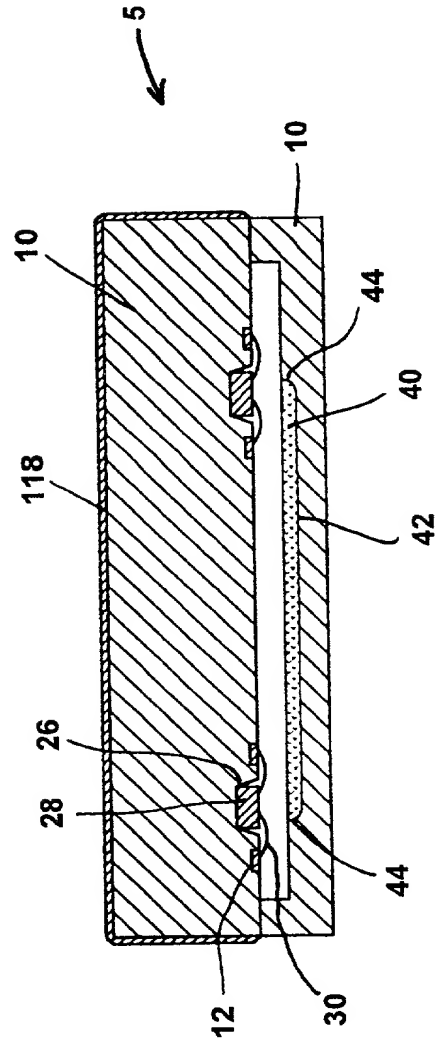


Fig. 13

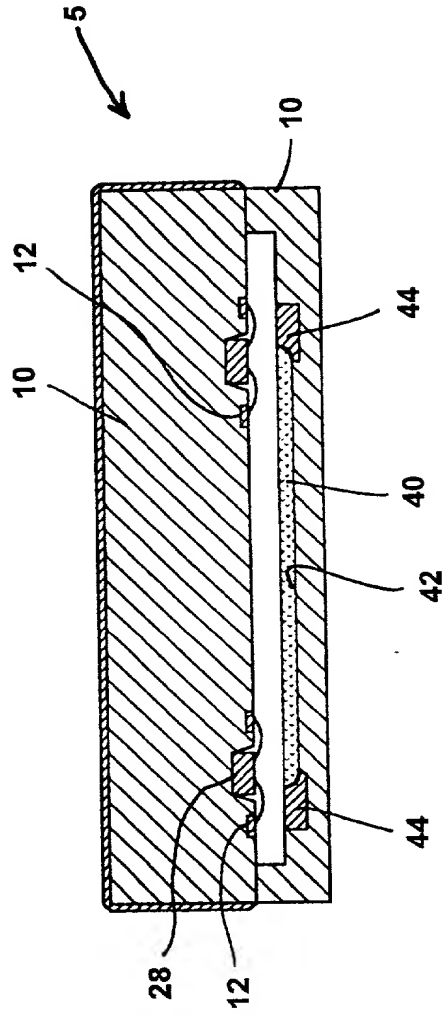


Fig. 14

